

Epitaxial AlAsSb for Spectroscopic Gamma Detectors

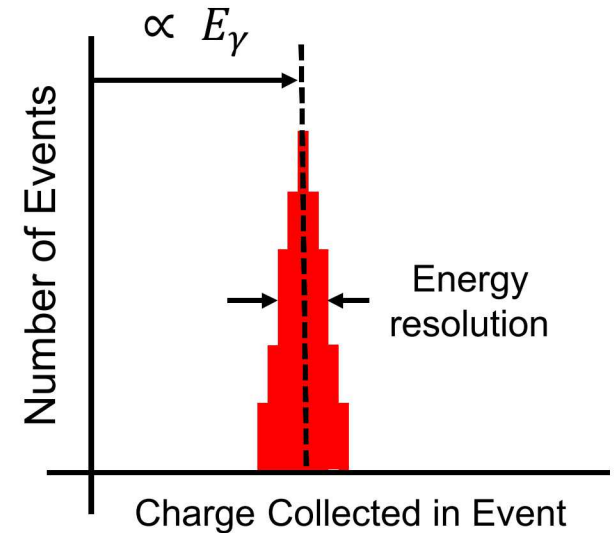
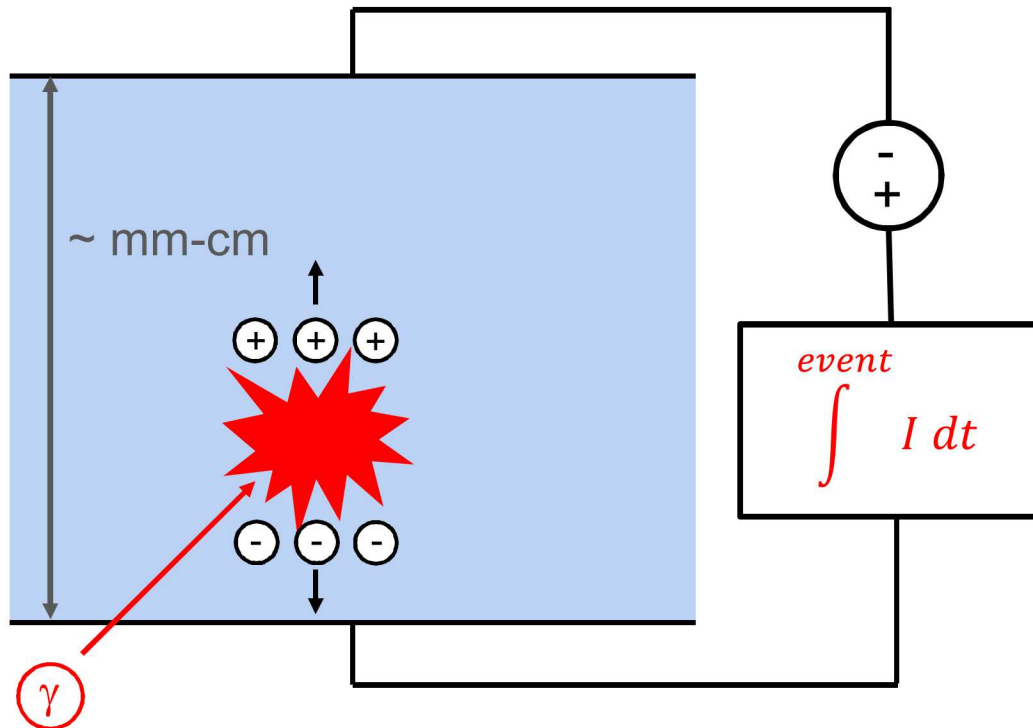
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Spectroscopic Semiconductor Gamma Radiation Detectors



Desirable material properties

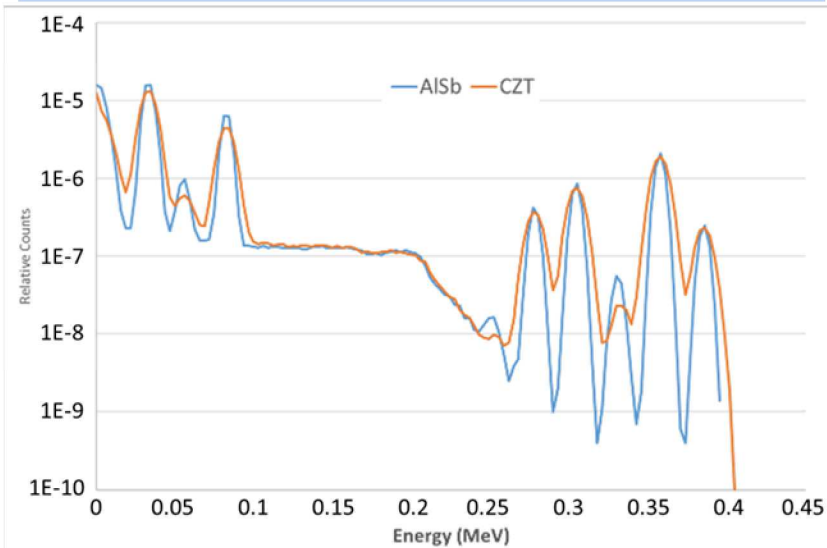
- High atomic number – improves gamma absorption
- Large mobility-lifetime products for both electrons and holes – reduces position dependence
- Low residual doping – allows large collection volume
- Large bandgap – reduces leakage current

Commonly bulk-grown HPGe (77 K), CdTe, CdZnTe

Epitaxial AlAsSb as a Gamma Detector Material

For Compact Sensor Applications

Simulated Ba-133 gamma ray spectra
for 1 cm³ CdZnTe and AlSb devices



**AlSb offers potential resolution
improvement of 40%**

Expected advantages over existing materials

- CdZnTe
 - Improved hole transport (hole mobility similar to electron mobility)
 - Improved Fano factor (reduced charge generation variability)
- HPGc
 - Improved gamma absorption
 - Higher-temperature operation
- Availability of heterostructure options (AlGaAsSb and InGaAsSb alloys)

Challenges

- Oxidation of exposed surface/edges
- Background doping concentration and trap density
- Lattice matching / compositional control of very thick layers
- Surface defect density
- Surface conductance

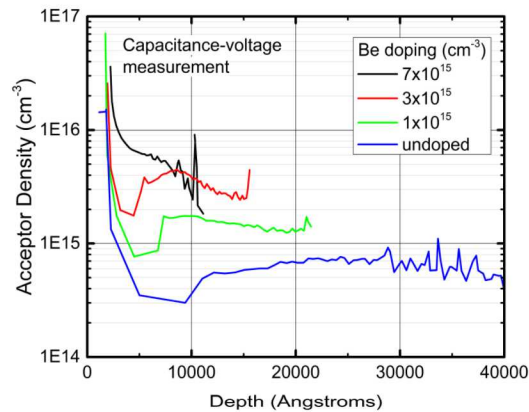
History

- Use in mid-IR lasers, microelectronics (FETs), and infrared detector (barrier diodes)
- Calculations suggest that Te-compensated material could have high resistivity
- AlSb bulk crystals have been grown

MBE Growth of AlAsSb on GaSb

C-V diode structures

InAsSb:Be p+
InAs:Be p+
1.4 μm AlAsSb:Be p
GaSb:un
GaSb:Te n substrate



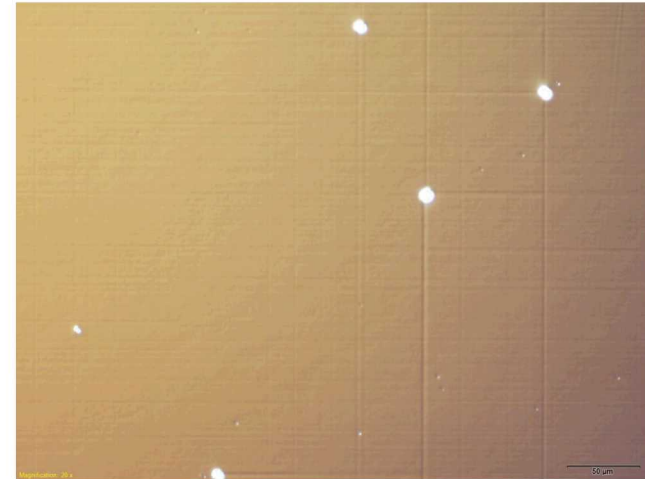
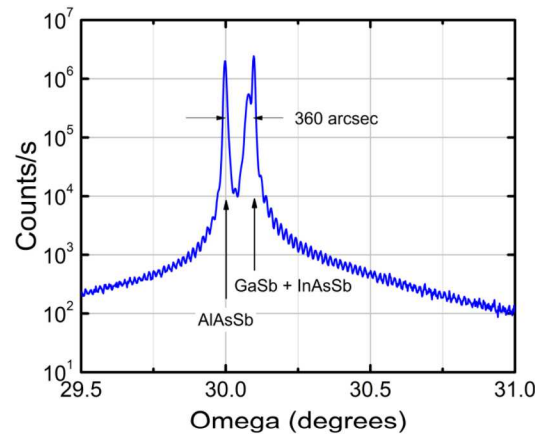
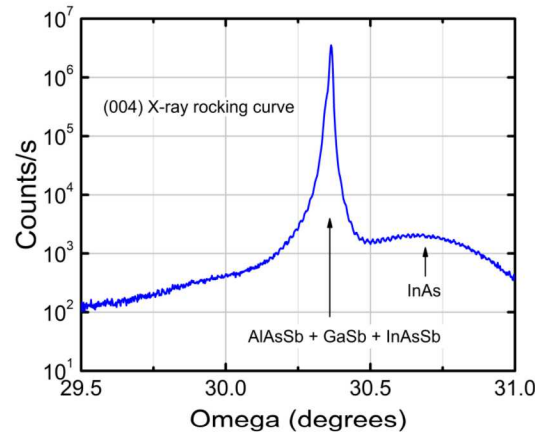
AlAsSb growth conditions

- 0.75 $\mu\text{m/hr}$
- T_s 520 $^{\circ}\text{C}$
- $\sim 1.3:1$ Sb:Al
- Sb cracker 800 $^{\circ}\text{C}$

Undoped material p-type $\sim 5 \times 10^{14} \text{ cm}^{-3}$

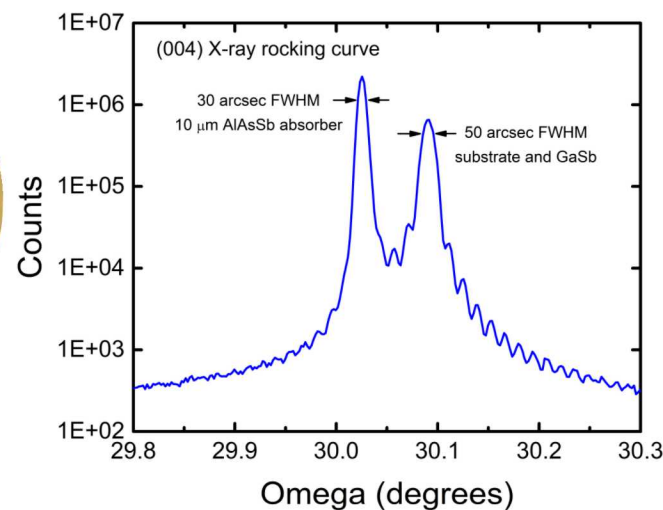
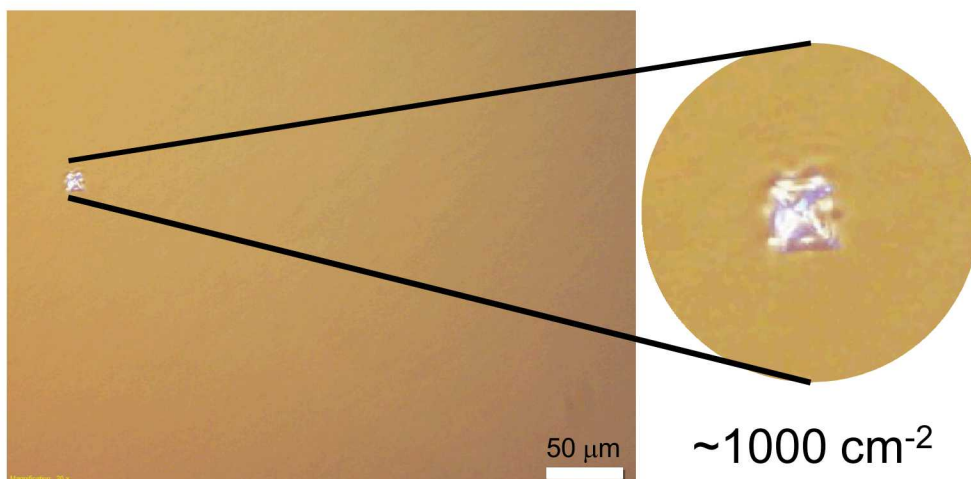
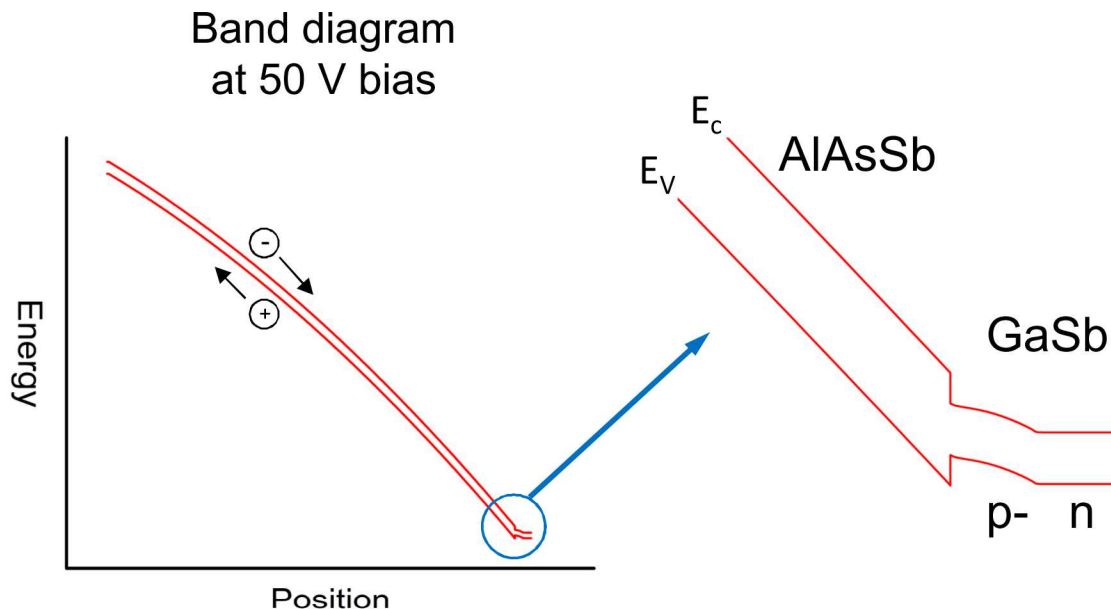
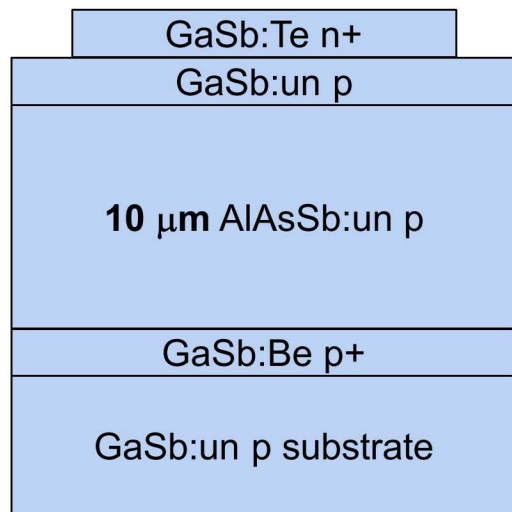
$$\text{CTE}_{\text{GaSb}} > \text{CTE}_{\text{AlAsSb}}$$

300K-lattice-matched films exhibit cracking



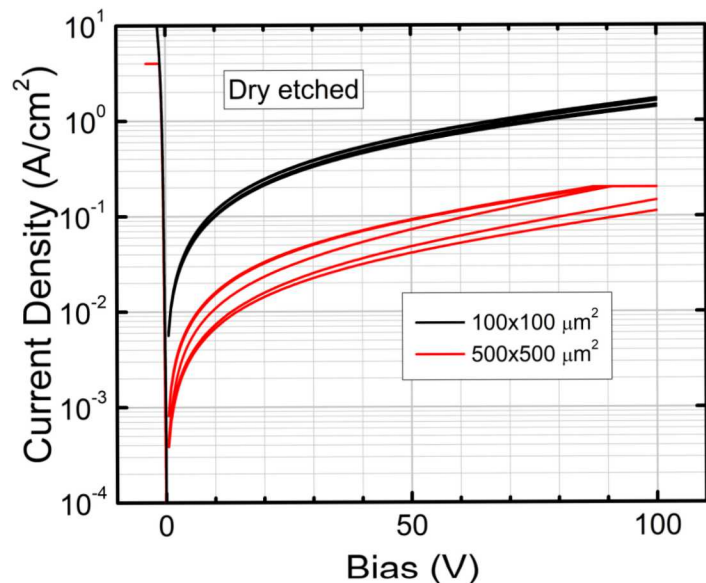
AlAsSb Diodes with Epitaxial Surface Passivation

- Heterojunction p-n diode
- No exposed AlAsSb



Diode Characteristics

Unintentionally doped AlAsSb

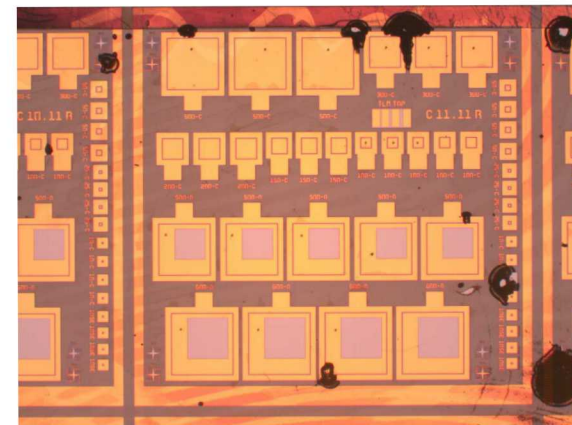
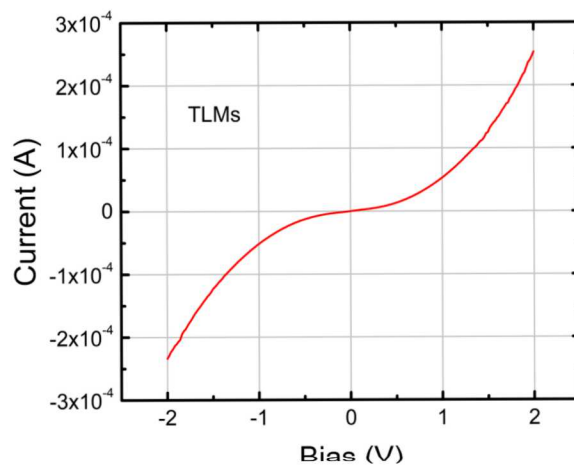
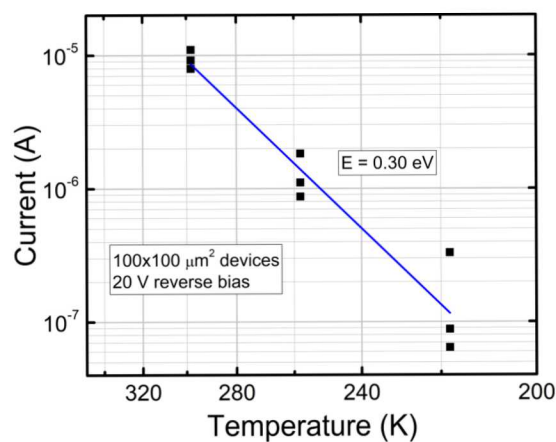
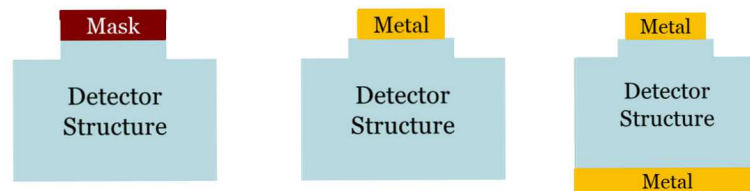


Diode processing

Wet: HCl/H_2O_2 (non-uniform, lower leakage)

Dry: Cl_2/Ar (uniform)

Metal: Ta 20 nm/Au 700 nm, top and bottom



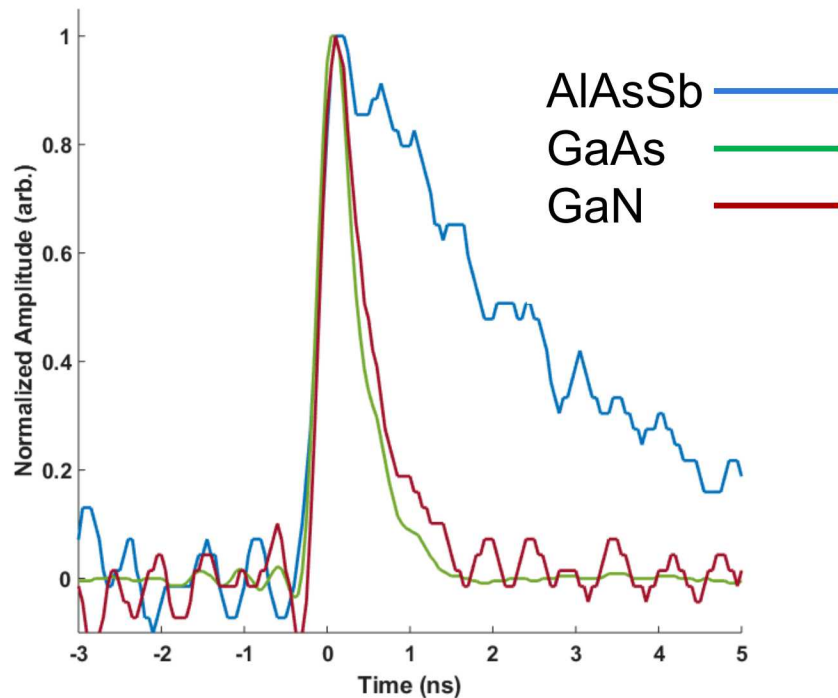
Diode X-ray AlAsSb Diode Photoresponse

“White” 1-100 keV beam

Time-resolved response

AlAsSb diode bias 2 V

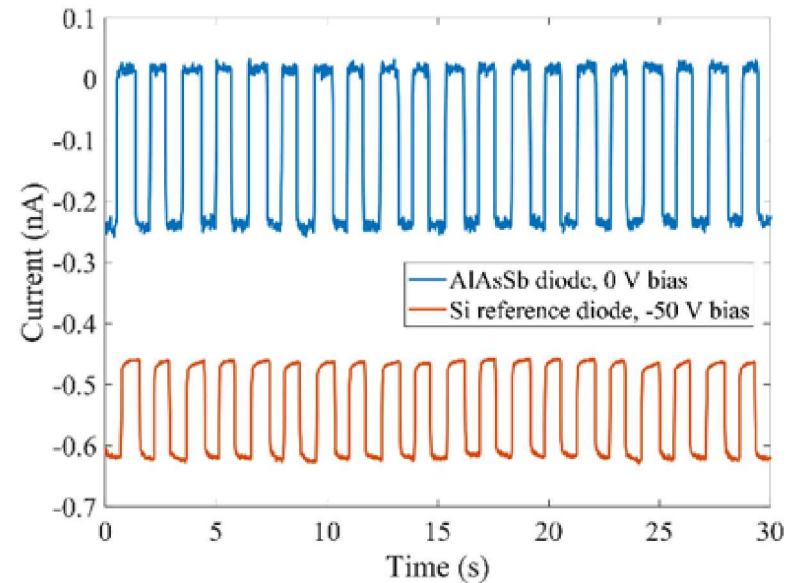
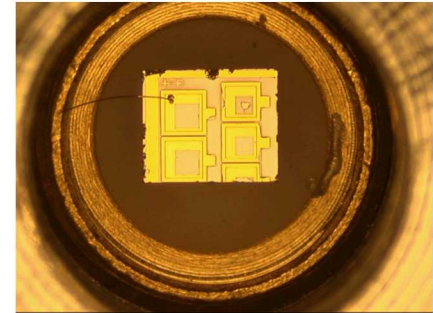
Low electric field limits speed



Mo K_{α} + K_{β} chopped source

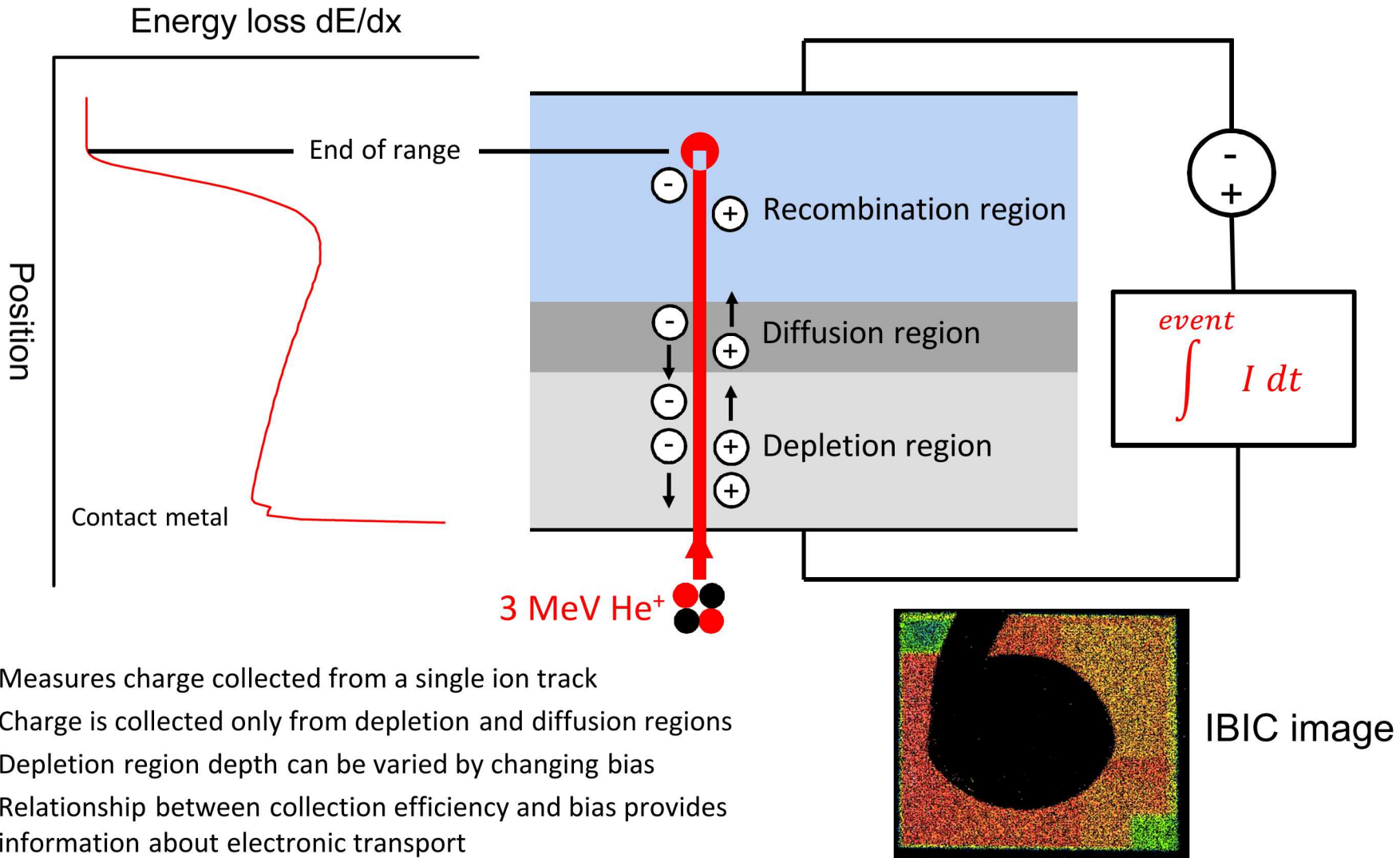
Zero-bias responsivity

similar to full depleted 25 μm Si diode



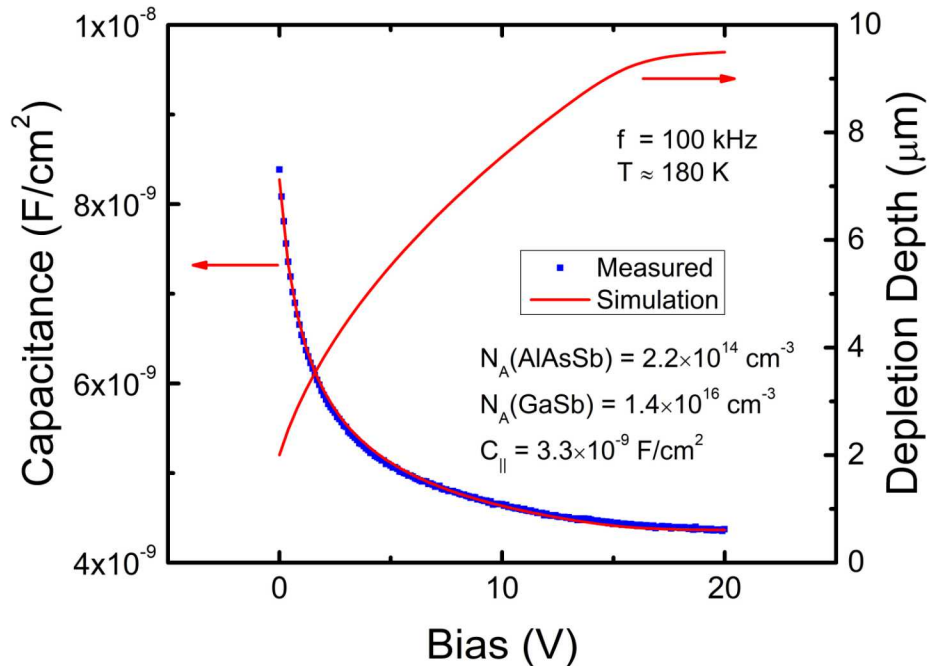
Ion Beam Induced Current Measurements

Charge Collection Efficiency Determination



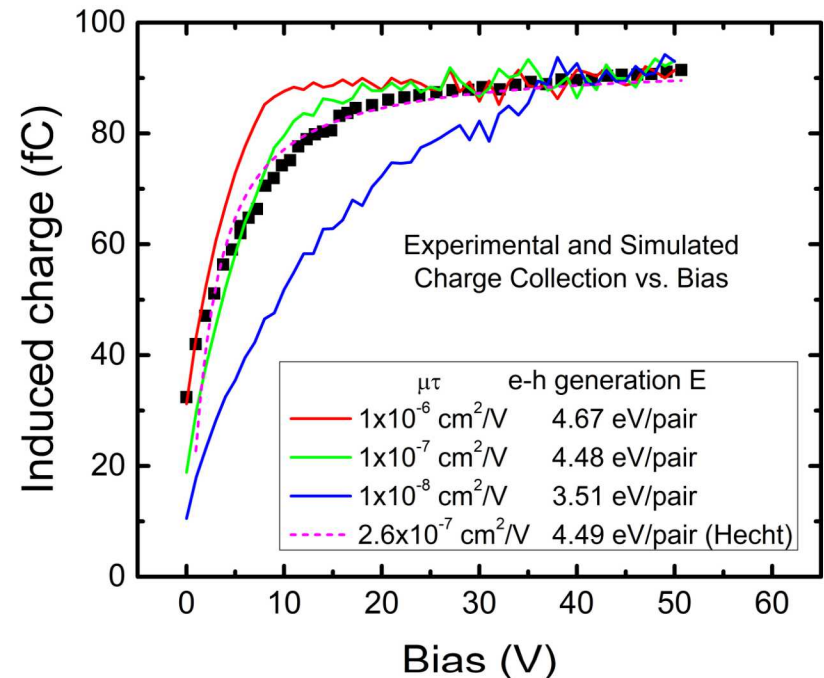
Determination of AlAsSb Electronic Mobility-Lifetime Product

$\mu\tau$ is estimated from ion-generated charge collection / bias relation at ~ 180 K



Capacitance-voltage fit determines

- AlAsSb background doping
- GaSb background doping
- Depletion depth vs. bias



Drift-diffusion simulation provides estimates of

- $\mu\tau \sim 10^{-7} \text{ cm}^2/\text{V}$ (assumed equal for electrons and holes)
 - Diffusion length $\sim 0.4 \mu\text{m}$
- Electron-hole pair generation energy $\sim 4.5 \text{ eV}$
 - 5.1 eV expected based on AlAsSb bandgap of 1.68 eV

Hecht equation fit yields similar results

- But condition of uniform electric field not satisfied

Perspectives on AlAsSb characteristics

Ballpark requirements for a good, thin spectroscopic gamma detector

- Energy resolution $< 1\%$
- Bias $< 100\text{ V}$
- γ detection efficiency $> 1\%$

AlAsSb layer thickness $d = 120\text{ }\mu\text{m}$

- $1 - \exp(-\alpha d) = 10^{-2}$

$\mu\tau \sim 10^{-4}\text{ cm}^2/\text{V}$ (need $\sim 500\times$ improvement)

- $E = V/d = 8.3 \times 10^3\text{ V/cm}$
- Want collection length $\mu\tau E \sim 100\times$ AlAsSb thickness $\rightarrow 1.2\text{ cm}$

Background carrier concentration $N_A \sim 1 \times 10^{13}\text{ cm}^{-3}$ (need $20\times$ reduction)

- Depletion depth $120\text{ }\mu\text{m}$ at 100 V

Leakage current ?

- Related to detector area

Conclusions

We have grown thick (10 μm) AlAsSb by MBE with

- Excellent compositional control ($\frac{dx_{\text{AlAs}}}{x_{\text{AlAs}}} \approx 0.01$)
- Defect density $\sim 1000 \text{ cm}^{-2}$
- Background carrier concentration $\sim 2 \times 10^{14} \text{ cm}^{-3}$

A novel heterostructure provided surface passivation for the AlAsSb

- Enabled simple processing
- Good diode characteristics
- Leakage currents need to be further reduced

Diodes exhibited good x-ray response

- Reduction in leakage current needed to enable measurements at high bias

$\mu\tau$ estimated with ion beam induced current measurements

- $\sim 2 \times 10^{-7} \text{ cm}^2/\text{V}$

Further improvements needed for desired detector characteristics

- 10x lower doping
- Much higher $\mu\tau$